10-18-2001 Docket No.: 56504 (71987) FORM PTO-1595 (Modified) (Rev. 03-01) **IEET** U.S. DEPARTMENT OF COMMERCE OMB No. 0651-0027 (exp.5/31/2002) P08A/REV03 Patent and Trademark Office 101878034 Tab settings 🔷 🔷 To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof. 1. Name of conveying party(ies): 2. Name and address of receiving party(ies): **Chien Ping HUANG** Chi Chuan WU Name: Siliconware Precision Industries Co., Ltd. Jui-Yu CHUANG Lien-Chih CHAN and Ming-Chih HSIEH Address: No. 123, Sec. 3, Da Fong Road, Tantzu Additional names(s) of conveying party(ies) Taichung, Taiwan, R.O.C. ☐ Yes ☒ No Nature of conveyance: Assignment Merger Security Agreement ☐ Change of Name City: _____ State/Prov.: ____ Other Country: _____ ZIP: ____ Execution Date: February 20, 2001 Additional name(s) & address(es) ☐ Yes ⊠ No Application number(s) or patent numbers(s): If this document is being filed together with a new application, the execution f the application is: October 9, 2001 Patent Application No. Filing date B. Patent No.(s) 10/12/2001 RMEBRAHT 00000030 09973151 Q2 FC:581 40.00 OP Additional numbers ☐ Yes ☒ No 5. Name and address of party to whom correspondence 6. Total number of applications and patents involved: concerning document should be mailed: Name: Peter F. Corless 7. Total fee (37 CFR 3.41):....\$ 40.00 Registration No. 33,860 Enclosed - Any excess or insufficiency should be credited or debited to deposit account Address: EDWARDS & ANGELL, LLP P.O. Box 9169 ☐ Authorized to be charged to deposit account 8. Deposit account number: City: Boston _____ State/Prov.: MA 04-1105 Country: USA ZIP: 02209 (Attach duplicate copy of this page if paying by deposit account) DO NOT USE THIS SPACE 9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Peter F. Corless (Reg. No. 33,860)

Name of Person Signing

Signature

Total number of pages including cover sheet, attachments, and

October 9, 2001

Date

ASSIGNMENT OF U.S. PATENT APPLICATION

	In consideration of the sum of One Dollar (\$1.00) in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned
Inventor(s) Full Name(s)	1.) Chien-Ping Huang. 2) Chi-Chuan Wu 3) Jui-Yu Chuang 4) Lien-Chih Chan 5) Ming-Chih Hsieh
Assignee Name and Address	hereby sell, assign and transfer to SILICONWARE PRECISION INDUSTRIES CO., LTD. No. 123, Sec. 3, Da Fong Rd., Tantzu, Taichung, Taiwan, R.O.C.
	(hereinafter called the Assignee) the entire right, title, and interest in and to any and all improvements whice are disclosed in the Application for United States Letters Patent entitled
Title of Invention	SEMICONDUCTOR PACKAGE WITH HEAT DISSIPATING STRUCTURE which application was
Compl ese either a) or b)	a) executed by the undersigned on the
	It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said Assignee. Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining proper patent protection.
Oat e	Signed at TAICHUNG this 20th day of FEB. 2001
nventor(s) iull ignature(s)	INVENTOR(5): Chi-Chean Wu Jui-Ty Chuong Lien-clik Chan Minythih Hzieh
litnesses' ull ignatures	WITNESSES:

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RECORDED: 10/09/2001

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